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**Application Information**

Title : METHODS AND APPARATUSES FOR MECHANICAL  
AND CHEMICAL-MECHANICAL PLANARIZATION OF  
MICROELECTRONIC-DEVICE SUBSTRATE  
ASSEMBLIES ON PLANARIZING PADS  
Total Drawing Sheets : 7  
Formal Drawings : YES  
Application Type : Utility  
Attorney Docket Number : 500077.12 (29222/US/11)  
Assigned : Yes (Large Entity)

**Representative Information**

Representative Customer No. : 27,076

**Continuity Information**

This application is a : divisional of  
>Application One : 10/300,344  
Filing Date : November 19, 2002  
which is a : divisional of  
>>Application Two : 09/854,390  
Filing Date : May 11, 2001  
Patent Number : 6,638,148  
which is a : continuation of  
>>>Application Three : 09/164,915  
Filing Date : October 1, 1998  
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